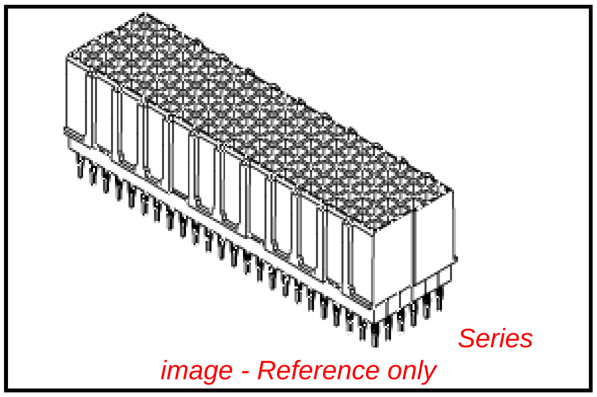
molex
one company > a world of innovation

This document was generated on 05/14/2010

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number:	**0737800226**
Status:	**Active**
Overview:	hdm
Description:	2.00mm (.079") Pitch HDM® Board-to-Board Daughtercard Receptacle, Vertical, Signal Module, 72 Circuits, Mounted Height 16.00mm (.630"), Pin Length 2.00mm (.079"), Solder Tail



Series image - Reference only

Documents:

3D Model
Test Summary (PDF)
Drawing (PDF)
Product Specification PS-73780-999 (PDF)
RoHS Certificate of Compliance (PDF)

General

Product Family	Backplane Connectors
Series	73780
Application	Daughtercard, Mezzanine
Comments	Solder Tail
Component Type	PCB Receptacle
Overview	hdm
Product Name	HDM®
Style	N/A

Physical

Circuits (Loaded)	72
Circuits (maximum)	72
Color - Resin	Black
Durability (mating cycles max)	250
First Mate / Last Break	No
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Copper-Nickel-Tin
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Number of Columns	12
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length (in)	0.079 In
PC Tail Length (mm)	2.00 mm
PCB Locator	No
PCB Retention	None
PCB Thickness Recommended (in)	0.063 In
PCB Thickness Recommended (mm)	1.60 mm
Packaging Type	Tube
Pitch - Mating Interface (in)	0.079 In
Pitch - Mating Interface (mm)	2.00 mm
Pitch - Term. Interface (in)	0.079 In
Pitch - Term. Interface (mm)	2.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.75
Plating min: Termination (µin)	100
Plating min: Termination (µm)	2.5
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes

EU RoHS
ELV and RoHS Compliant
REACH SVHC
Contains SVHC: No
Halogen-Free Status
Not Reviewed

China RoHS

Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, click here

Please visit the Contact Us section for any non-product compliance questions.

Search Parts in this Series
73780Series

Mates With
HDM® Board-to-Board Backplane Header 73642 , 73643 , 73644 , 73942 , 73943 , 73944 , 74349 , 74428. HDM® Board-to-Board Stacking Header 73769 , 73770 , 73782 , 73783 , 73771

Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole

Electrical

Current - Maximum per Contact	15A, 1A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)	5
Lead-free Process Capability	Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	1
Process Temperature max. C	260

Material Info

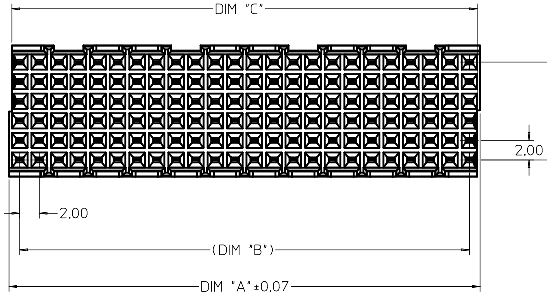
Reference - Drawing Numbers

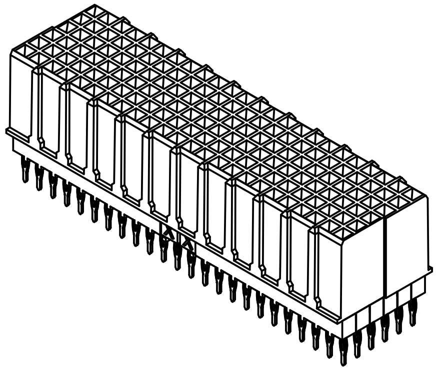
Product Specification	PS-73780-999
Sales Drawing	SD-73780-004

HDM and High Density Metric are trademarks of Amphenol Corporation

This document was generated on 05/14/2010

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION





MATERIAL NUMBER ASSIGNMENT

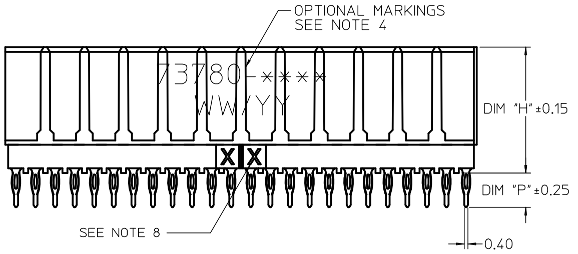
7 3 7 8 0 - ∗ ∗ ∗ ∗

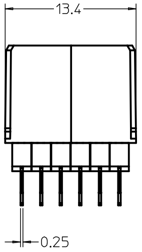
0 = 72 CKT SOLDER TAIL
1 = 144 CKT SOLDER TAIL

1 = NO MARKINGS
2 = MARKINGS

DIM "P"
2 = 2.00
3 = 2.50
4 = 3.00
5 = 3.50
6 = 4.00
0 = 6.00

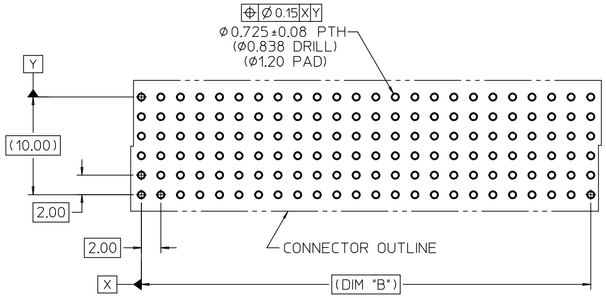
DIM "H"
3 = 13.0
4 = 14.0
5 = 15.0
6 = 16.0
7 = 17.0





NOTES:

1. MATERIALS: HOUSING - LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED, UL94V-0, COLOR: BLACK
2. FINISH: SELECTIVE GOLD (Au) IN CONTACT AREA, .76 MICROMETER MINIMUM THICKNESS; SELECTIVE TIN (Sn), 2.50 MINIMUM THICKNESS ON SOLDER TAILS, NICKEL (Ni) OVERALL.
3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73780-999.
4. MARKINGS SHOWN FOR REFERENCE ONLY. SEE MATERIAL NUMBER ASSIGNMENT DIAGRAM FOR CORRECT NUMBER. MARKINGS TO INCLUDE MATERIAL NUMBER AND DATE CODE AND CAN BE LOCATED ANYWHERE ON PART, IN ANY ORIENTATION.
5. 73780-∗∗∗7 AND -∗∗0∗ PARTS TO BE PACKAGED IN TUBES PER PK-70873-0872. ALL OTHER PARTS TO BE PACKAGED IN TUBES PER PK-70873-0900.
6. 144-CIRCUIT HDM DAUGHTERCARD STACKING MODULE WITH PRESS-FIT TAILS SHOWN FOR ILLUSTRATION PURPOSES ONLY.
7. TRUE POSITION OF PC TAILS IS INSPECTED USING GAUGE NUMBER 73727-0014.
8. MARKINGS MAY BE ORIENTED TO EITHER SIDE OF CONNECTOR.



PCB LAYOUT: COMPONENT SIDE

MATERIAL NUMBER	CIRCUIT SIZE	DIM "A"	DIM "B"	DIM "C"
73780-1∗∗∗	144	48.17	46.00	47.6
73780-0∗∗∗	72	24.17	22.00	23.6

REV	DESCRIPTION
B	UPDATE TO S.T. ONLY EC NO: UCP2010-1860 2010/01/22 DRWN:JMELTON 05/07/08 CH'KD:SDANNELLEY APPR:SMILLER 2010/02/08

QUALITY SYMBOLS
∇_{A}^{F} =0
∇_{C}^{F} =0
∇_{P}^{F} =0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.05	± ---
1 PLACE	± 0.10	± ---
ANGULAR ± 2 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	**MM ONLY**
SCALE	**4:1**
DESIGN UNITS	**METRIC**
	THIRD ANGLE PROJECTION
DRAWN BY	MIBARRA
DATE	05/07/08
CHECKED BY	BSMART
DATE	05/07/08
APPROVED BY	SMILLER
DATE	2010/02/08
TITLE	SALES ASSEMBLY, HDM DAUGHTERCARD STACKING MODULE, SOLDER TAIL
	MOLEX INCORPORATED
MATERIAL NO.	SEE TABLE
DOCUMENT NO.	SD-73780-004
SHEET NO.	1 OF 1
SIZE	D

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION